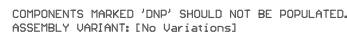


1. BOARD DIMENSION : 122MM X 66MM.
2. VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED, PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED VIA TENTING/COVERING REQUIREMENTS.
3. ALL VIAS ARE TENTED ON BOTH SIDES UNLESS OTHERWISE SOLDER MASK IS OPENED IN GERBER.
4. TRACES WITH 6.3MIL TO BE 50 OHMS +/-10% SINGLE ENDED ON TOP LAYER & BOTTOM LAYER (L1 & L14).
5. TRACES WITH 4.5MIL TO BE 50 OHMS +/-10% SINGLE ENDED ON SIGNAL1, SIGNAL2, SIGNAL3 & SIGNAL4 LAYERS (L3, L5, L10 & L12).
6. TRACES WITH 7MIL AND 14MIL SEPERATION TO BE 90 OHMS +/-10% DIFFERENTIAL ON EXTERNAL LAYER(L1).
7. TRACES WITH 5MIL AND 9MIL SEPERATION TO BE 90 OHMS +/-10% DIFFERENTIAL ON INTERNAL LAYER(L3).
8. TRACES WITH 5.4MIL AND 11.4MIL SEPERATION TO BE 100 OHMS +/-10% DIFFERENTIAL ON EXTERNAL LAYERS(L1 & L14).
9. TRACES WITH 4MIL AND 10MIL SEPERATION TO BE 100 OHMS +/-10% DIFFERENTIAL ON INTERNAL LAYERS(L3 & L12).
10. 8.01MIL VIAS NEED TO BE FILLED WITH NON-CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001 ON BOTTOM SIDE ONLY AND +0.000/-0.003 ON TOP SIDE. MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.

221 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.  
222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.  
225 ■ Indication provided for the DR components at their cathode side.



PCB VIEWED FROM TOP SIDE	BOARD # : .PRJ_Number	REV : .PCB_Rev SUN REV: Not in version control
MSP-0000000000 Top	TID #: .TID	
PLOT NAME = Multilayer Composite Print	GENERATED : 1/26/2024 2:09:35 PM	TEXAS INSTRUMENTS

**DESIGN INFORMATION**

MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 5 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNUULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL  
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

**MATERIAL:**

☐ FR-408 ☒ FR-4 High Tg ☐ OTHER \_\_\_\_\_

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER 93 MIL +/-10%

TOLERANCE: ☒ ANSI PC-6012 TYPE 3 CLASS 2  
☐ OTHER +/- \_\_\_\_\_

BOW & TWIST: ☒ ANSI PC-6012 TYPE 3 CLASS 2  
☐ OTHER +/- \_\_\_\_\_

**DRAWING:**

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH COPPER THICKNESS: 20-30 um ☐ OTHER \_\_\_\_\_

**BOARD FINISH:**

SILKSCREEN: ☒ TOP ☐ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER \_\_\_\_\_

SOLDER RESIST COLOR: ☐ GREEN ☐ OTHER BLUE  
☐ MATTE ☒ SEMI-GLOSS

**SURFACE FINISH:** ☒ IMMERSION GOLD (ENIG) ☐ ENERP  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER \_\_\_\_\_

**ARRAY/PANEL:** ☐ CUT AND TRIM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☒ V. SCORE

**CERTIFICATION:** MATERIALS AND WORKMANSHIP FOR ALL PCBs  
TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI PC-A-600F class -> ☐ 1 ☒ 2 ☐ 3  
☐ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL D NUMBER

**ADDITIONAL REQUIREMENTS:**  
MICROSECTION: ☒ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☒ XX MIL. WAS REQUIRES NON-CONDUCTIVE FILL AND PLANARIZE

☒ XX MIL. WAS REQUIRES CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL. TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (IF LAYERS) XX MIL. WIDE, XX MIL. SPACE

☐ TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE